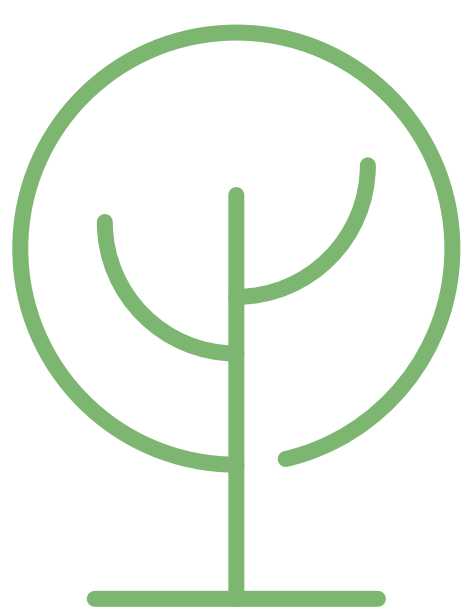
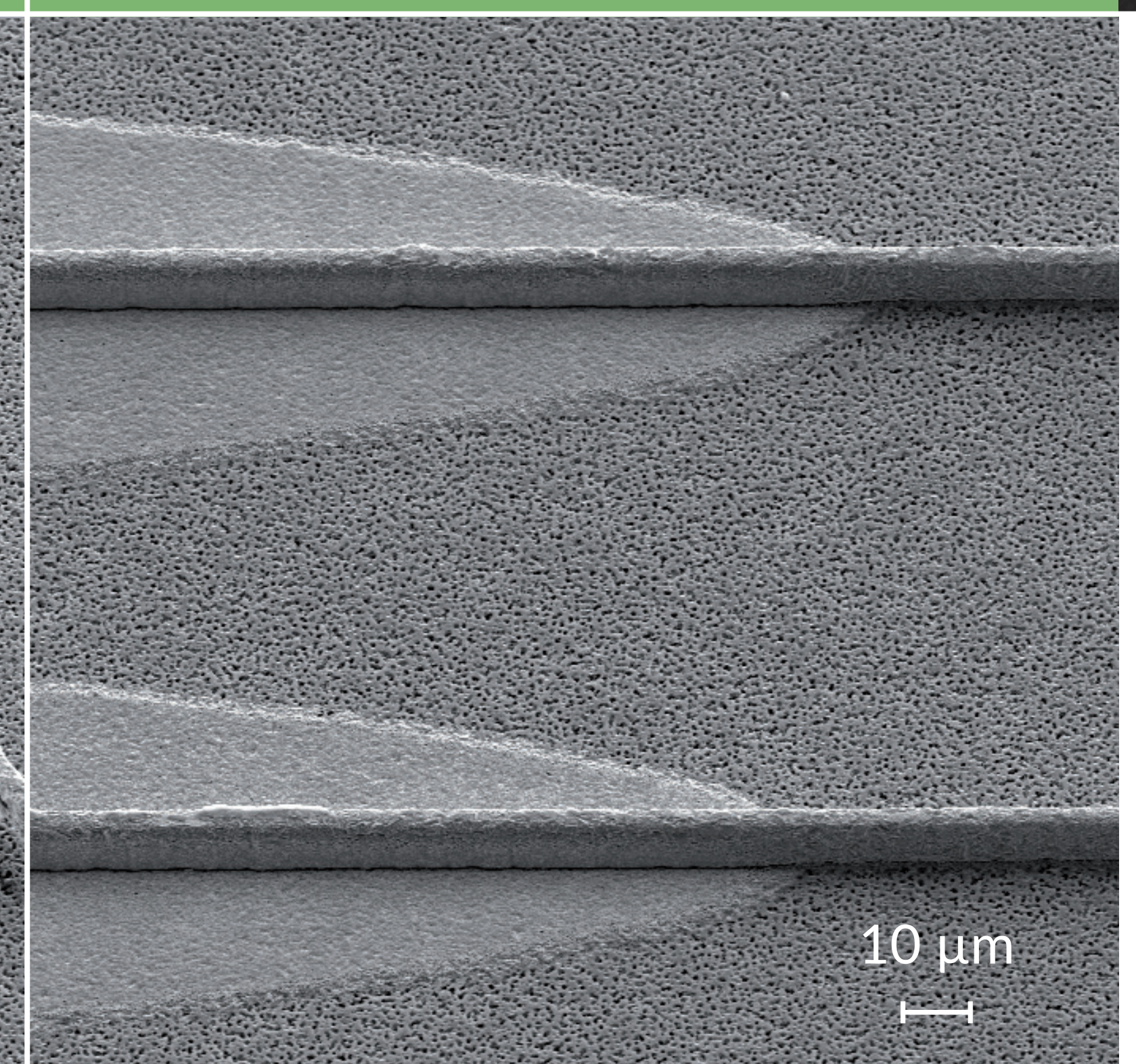
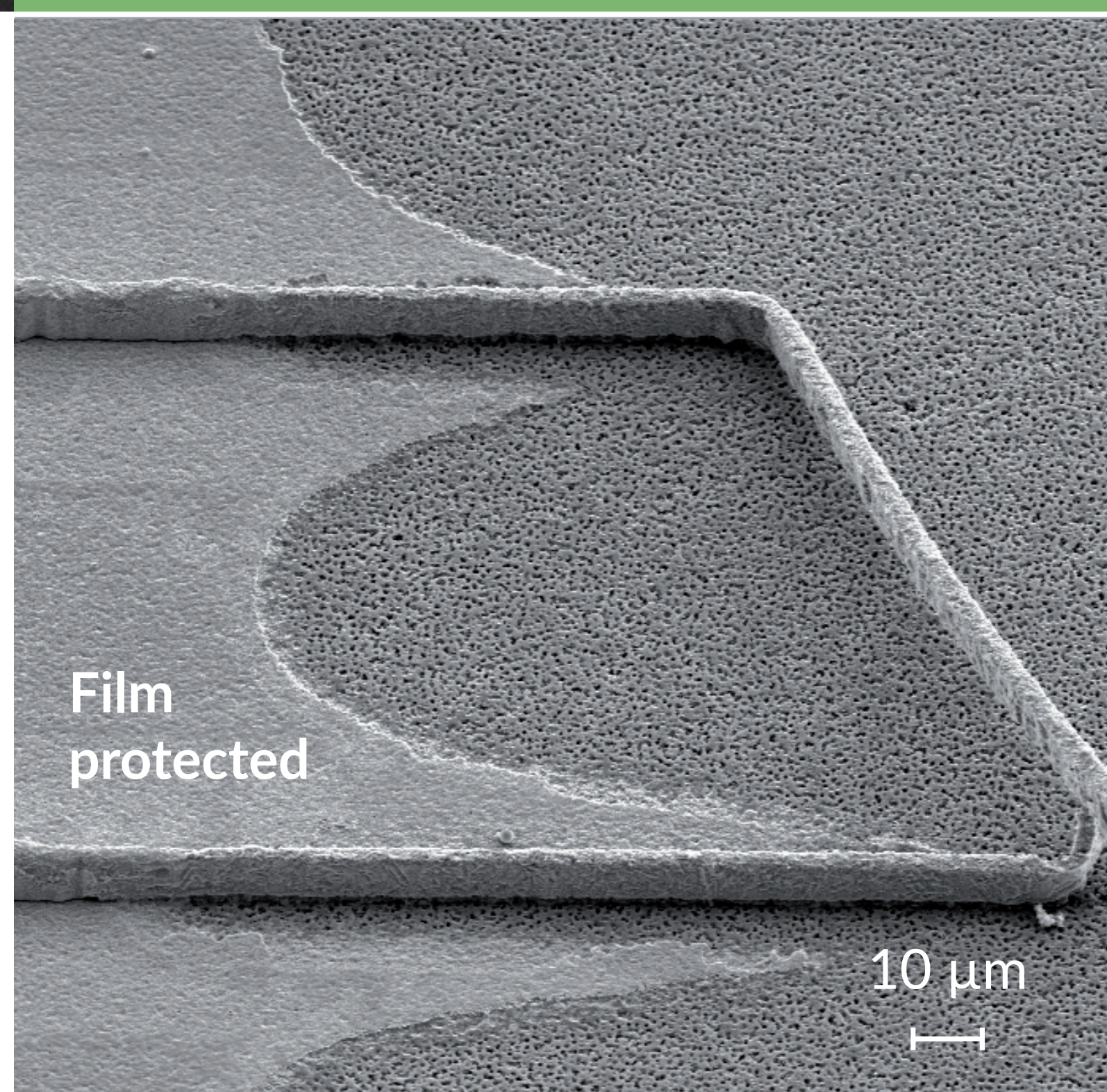


Differential etching for advanced SAP* manufacturing

Conventional differential etchant:
undercut problems, L/S 6/100 μm

EcoFlash[®] S 300: optimal performance
and minimal LWR, L/S 6/100 μm



Reduce waste water while saving costs with unique iron-based process and hydrogen peroxide regeneration of working solution

Advanced differential etching

EcoFlash[®] S 300 is a differential etchant based on iron sulfate. It is unique and specially designed to maintain the conductors undercut-free and in their original shape. Thus EcoFlash[®] S 300 is able to improve yields, enable lower line/space manufacturing. It is possible to regenerate the iron-based solution using hydrogen peroxide, thus significantly reducing the use of chemicals and the generation of waste water vs. conventional products.

Features and benefits

- Simple one-step and low-temperature process
- Quick removal of copper seed layer without causing undercuts of conductors
- Lower production and waste treatment cost through simple solution regeneration
- Stable easy to control etch rate
- High process stability and reliable operation

*SAP = semi-additive process